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Series/Type: B37931

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B37931K9224K060		2008-08-01	2009-07-31	2009-10-31
B37931K9224K070		2008-08-01	2009-07-31	2009-10-31
B37931K0224K060		2008-08-01	2009-07-31	2009-10-31



Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B37931K0224K070		2008-08-01	2009-07-31	2009-10-31
B37931K5104K060		2008-08-01	2009-07-31	2009-10-31
B37931K5104K070		2008-08-01	2009-07-31	2009-10-31
B37941K9224K060		2008-08-01	2009-07-31	2009-10-31
B37941K9224K070		2008-08-01	2009-07-31	2009-10-31
B37941K9334K060		2008-08-01	2009-07-31	2009-10-31
B37941K9334K070		2008-08-01	2009-07-31	2009-10-31
B37941K9474K060		2008-08-01	2009-07-31	2009-10-31
B37941K9474K070		2008-08-01	2009-07-31	2009-10-31
B37941K9105K062		2008-08-01	2009-07-31	2009-10-31
B37941K9105K072		2008-08-01	2009-07-31	2009-10-31
B37941K0224K060		2008-08-01	2009-07-31	2009-10-31
B37941K0224K070		2008-08-01	2009-07-31	2009-10-31
B37941K0334K060		2008-08-01	2009-07-31	2009-10-31
B37941K0334K070		2008-08-01	2009-07-31	2009-10-31
B37941K0474K060		2008-08-01	2009-07-31	2009-10-31
B37941K0474K070		2008-08-01	2009-07-31	2009-10-31
B37941K0105K062		2008-08-01	2009-07-31	2009-10-31
B37941K0105K072		2008-08-01	2009-07-31	2009-10-31
B37941K5224K060		2008-08-01	2009-07-31	2009-10-31
B37941K5224K070		2008-08-01	2009-07-31	2009-10-31
B37941K5334K062		2008-08-01	2009-07-31	2009-10-31
B37941K5334K072		2008-08-01	2009-07-31	2009-10-31
B37941K5474K062		2008-08-01	2009-07-31	2009-10-31
B37941K5474K072		2008-08-01	2009-07-31	2009-10-31
B37941K5105K062		2008-08-01	2009-07-31	2009-10-31
B37941K5105K072		2008-08-01	2009-07-31	2009-10-31
B37872K9105K062		2008-08-01	2009-07-31	2009-10-31
B37872K9105K072		2008-08-01	2009-07-31	2009-10-31
B37872K9225K062		2008-08-01	2009-07-31	2009-10-31
B37872K9225K072		2008-08-01	2009-07-31	2009-10-31
B37872K0105K062		2008-08-01	2009-07-31	2009-10-31
B37872K0105K072		2008-08-01	2009-07-31	2009-10-31
B37872K0225K062		2008-08-01	2009-07-31	2009-10-31
B37872K0225K072		2008-08-01	2009-07-31	2009-10-31
B37872K5105K062		2008-08-01	2009-07-31	2009-10-31
B37872K5105K072		2008-08-01	2009-07-31	2009-10-31

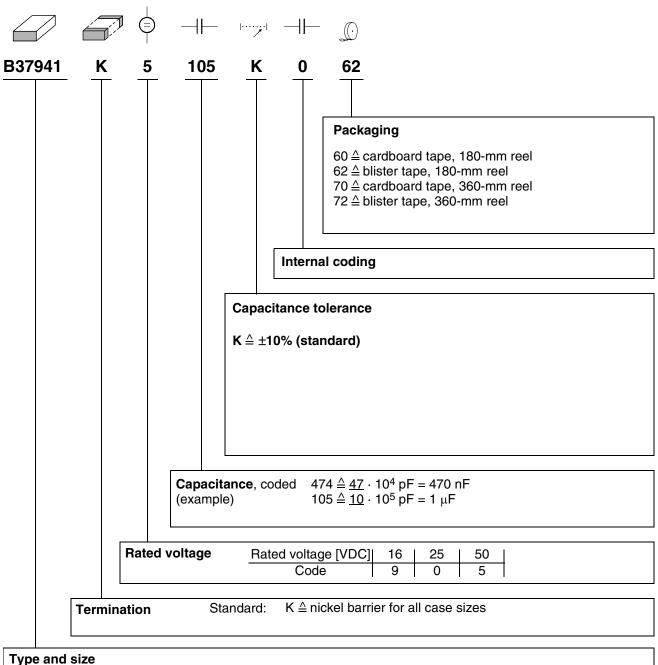
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B 4 1 1 1 1		
Militiave	r coramic	CONSCITATE
		capacitors

Chip

HighCV; X7R

Ordering code system



Type and size	
Chip size (inch / mm)	Temperature characteristic X7R
0603 / 1608 0805 / 2012 1206 / 3216	B37931 B37941 B37872



Chip

HighCV; X7R



Features

- Characteristic of class 2 dielectric
- Highest possible capacitance to rated voltage ratio
- High capacitance values up to 2.2 μF
- Voltage rating from 16 V to 50 V
- To AEC-Q200



Applications

Coupling and bypass filters

Termination

■ For soldering: Nickel barrier terminations (Ni)

Options

Other capacitance values on request

Delivery mode

■ Cardboard and blister tape (blister tape for chip thickness ≥1.2 ±0.1 mm)

Electrical data

Temperature characteristic		X7R	
Max. relative capacitance change			
within -55 °C to +125 °C	∆C/C	±15	%
Climatic category (IEC 60068-1)		55/125/56	
Standard		EIA	
Dielectric		Class 2	
Rated voltage ¹⁾	V_{R}	16; 25; 50	VDC
Test voltage	V_{test}	2.5 · V _R /5 s	VDC
Capacitance range	C _R	100 nF 2.2 μF	
Dissipation factor (limit value)	$tan \delta$	$<$ 50 · 10 ⁻³ for \le 25 V	
		$< 25 \cdot 10^{-3}$ for 50 V	
Insulation resistance ²⁾ at +25 °C	R _{ins}	>104	$M\Omega$
Time constant ²⁾ at +25 °C	τ	>500	s
Operating temperature range	T _{op}	−55 +125	°C
Ageing ³⁾		yes	

¹⁾ Note: No operation on AC line.

²⁾ For $C_R > 10$ nF the time constant $\tau = C \cdot R_{ins}$ is given.

³⁾ Refer to chapter "General technical information", "Ageing".



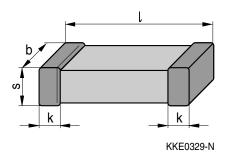


HighCV; X7R

Capacitance tolerances

Code letter	K (standard)
Tolerance	±10%

Dimensional drawing



Dimensions (mm)

Case size	(inch) (mm)	0603 1608	0805 2012	1206 3216
		1.6 ±0.15	2.00 ±0.20	3.2 ±0.20
b		0.8 ±0.10	1.25 ± 0.15	1.6 ±0.15
S		0.8 ±0.10	1.35 max.	1.80 max.
k		0.1 -0.4	0.13 -0.75	0.25 -0.75

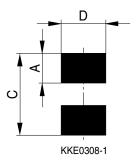
Tolerances to CECC 32101-801



HighCV; X7R



Recommended solder pad



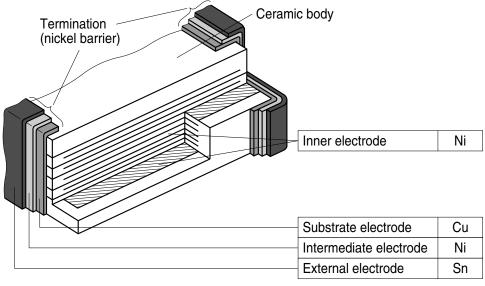
Recommended dimensions (mm) for reflow soldering

Case size	(inch/mm)	Туре	А	С	D
	0603/1608	single chip	0.6 0.7	1.8 2.20	0.6 0.8
	0805/2012	single chip	0.6 0.7	2.2 2.60	0.8 1.1
	1206/3216	single chip	0.8 0.9	3.8 4.32	1.0 1.4

Recommended dimensions (mm) for wave soldering

Case size	(inch/mm)	Туре	А	С	D
	0603/1608	single chip	0.8 0.9	2.2 2.8	0.6 0.8
	0805/2012	single chip	0.9 1.0	2.8 3.2	0.8 1.1
	1206/3216	single chip	1.0 1.1	4.2 4.8	1.0 1.4

Termination



KKE0342-F





HighCV; X7R

Product range for HighCV chip capacitors, X7R

Size ¹⁾									
inch		0603			0805			1206	
mm		1608			2012			3216	
Туре		B37931			B37941			B37872	
C _R (VDC)	16	25	50	16	25	50	16	25	50
100 nF									
220 nF									
330 nF									
470 nF									
1.0 μF									
2.2 μF									

 $[\]frac{1) \ \ l \times b \ (inch) \ / \ l \times b \ (mm)}{1}$



HighCV; X7R; 0603 to 1206



Ordering codes and packing for HighCV, X7R, 16, 25 and 50 VDC, nickel barrier terminations

		Chip thickness	Cardboard tape,	Cardboard tape,
		·	Ø 180-mm reel	Ø 360-mm reel
			** <u></u> 60	** ≙ 70
C _R ¹⁾	Ordering code	mm	pcs/reel	pcs/reel
Case size (0603, 16 VDC			
220 nF	B37931K9224K0**	0.8 ±0.1	4000	16000
Case size (0603, 25 VDC	<u> </u>		•
220 nF	B37931K0224K0**	0.8 ±0.1	4000	16000
Case size (0603, 50 VDC	1	1	1
100 nF	B37931K5104K0**	0.8 ±0.1	4000	16000
Case size (0805, 16 VDC	1	1	1
220 nF	B37941K9224K0**	0.8 ±0.1	4000	16000
330 nF	B37941K9334K0**	0.8 ±0.1	4000	16000
470 nF	B37941K9474K0**	0.8 ±0.1	4000	16000
1.0 μF	B37941K9105K0**	1.2 ±0.1	30002)	12000 ³⁾
Case size (0805, 25 VDC	1	1	1
220 nF	B37941K0224K0**	0.8 ±0.1	4000	16000
330 nF	B37941K0334K0**	0.8 ±0.1	4000	16000
470 nF	B37941K0474K0**	0.8 ±0.1	4000	16000
1.0 μF	B37941K0105K0**	1.2 ±0.1	30002)	12000 ³⁾
Case size (0805, 50 VDC			
220 nF	B37941K5224K0**	0.8 ±0.1	4000	16000
330 nF	B37941K5334K0**	1.2 ±0.1	30002)	12000 ³⁾
470 nF	B37941K5474K0**	1.2 ±0.1	30002)	12000 ³⁾
1.0 μF	B37941K5105K0**	1.2 ±0.1	30002)	120003)
Case size	1206, 16 VDC	<u>.</u>		•
1.0 μF	B37872K9105K0**	1.2 ±0.1	30002)	120003)
2.2 μF	B37872K9225K0**	1.2 ±0.1	30002)	120003)
Case size	1206, 25 VDC			
1.0 μF	B37872K0105K0**	1.2 ±0.1	30002)	12000 ³⁾
2.2 μF	B37872K0225K0**	1.2 ±0.1	30002)	12000 ³⁾
Case size	1206, 50 VDC			
1.0 μF	B37872K5105K0**	1.2 ±0.1	30002)	12000 ³⁾
			-	

¹⁾ Other capacitance values on request.

²⁾ Blister tape, 180-mm reel, ordering code ** ≜ 62
3) Blister tape, 330-mm reel, ordering code ** ≜ 72

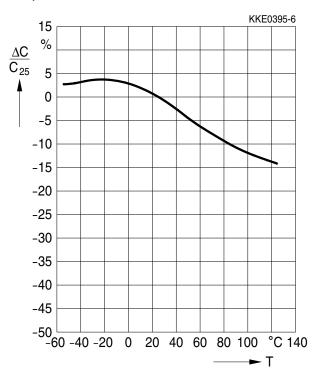




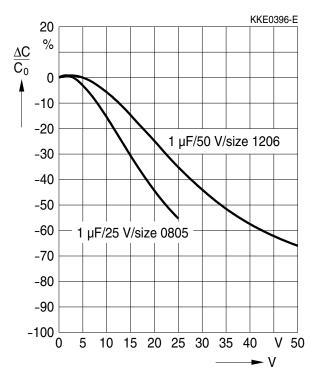
HighCV; X7R

Typical characteristics for HighCV X7R¹⁾

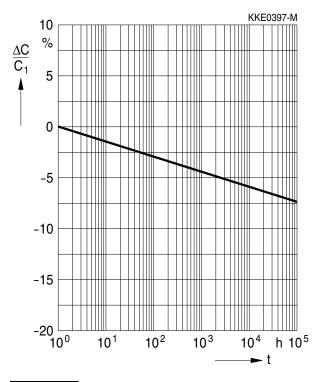
Capacitance change $\Delta \text{C/C}_{25}$ versus temperature T



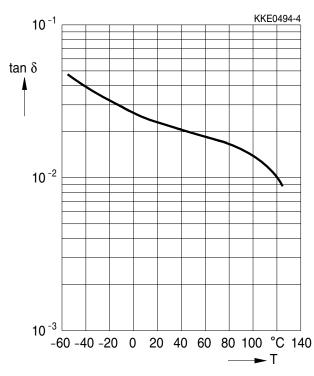
Capacitance change $\Delta C/C_0$ versus superimposed DC voltage V



Capacitance change $\Delta C/C_1$ versus time t



Dissipation factor tan δ versus temperature T



¹⁾ For more detailed information on frequency behavior and characteristics see www.epcos.com/mlcc_impedance.

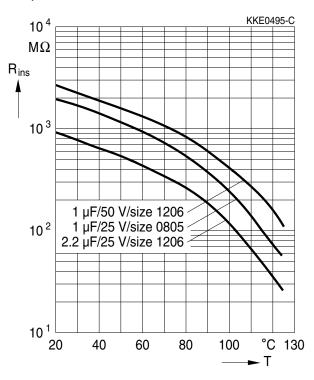


HighCV; X7R

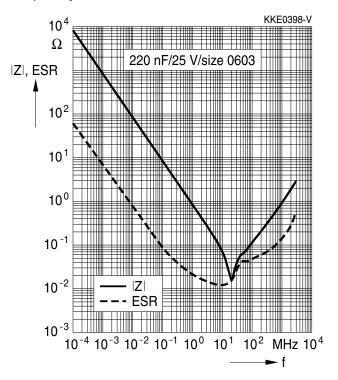


Typical characteristics for HighCV X7R¹⁾

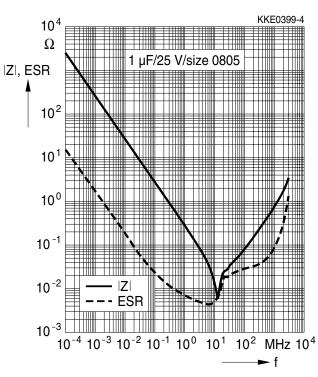
Insulation resistance R_{ins} versus temperature T



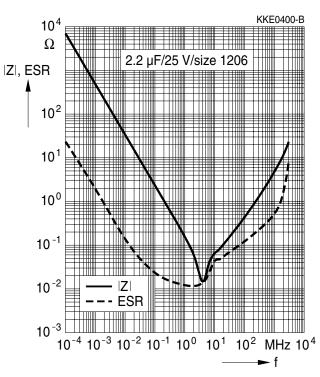
Impedance |Z| and ESR versus frequency f



Impedance |Z| and ESR versus frequency f



Impedance |Z| and ESR versus frequency f



¹⁾ For more detailed information on frequency behavior and characteristics see www.epcos.com/mlcc_impedance.



Cautions and warnings

Notes on the selection of ceramic capacitors

In the selection of ceramic capacitors, the following criteria must be considered:

- 1. Depending on the application, ceramic capacitors used to meet high quality requirements should at least satisfy the specifications to AEC-Q200. They must meet quality requirements going beyond this level in terms of ruggedness (e.g. mechanical, thermal or electrical) in the case of critical circuit configurations and applications (e.g. in safety-relevant applications such as ABS and airbag equipment or durable industrial goods).
- 2. At the connection to the battery or power supply (e.g. clamp 15 or 30 in the automobile) and at positions with stranding potential, to reduce the probability of short circuits following a fracture, two ceramic capacitors must be connected in series and/or a ceramic capacitor with integrated series circuit should be used. The MLSC from EPCOS contains such a series circuit in a single component.
- 3. Ceramic capacitors with the temperature characteristics Z5U and Y5V do not satisfy the requirements to AEC-Q200 and are mechanically and electrically less rugged than C0G or X7R/X8R ceramic capacitors. In applications that must satisfy high quality requirements, therefore, these capacitors should not be used as discrete components (see the chapter "Effects on mechanical, thermal and electrical stress", point 1.4).
- 4. For ESD protection, preference should be given to the use of multilayer varistors (MLV) (see the chapter "Effects on mechanical, thermal and electrical stress", point 1.4).
- 5. An application-specific derating or continuous operating voltage must be considered in order to cushion (unexpected) additional stresses (see the chapter "Reliability").

The following should be considered in circuit board design

- 1. If technically feasible in the application, preference should be given to components having an optimal geometrical design.
- 2. At least FR4 circuit board material should be used.
- 3. Geometrically optimal circuit boards should be used, ideally those that cannot be deformed.
- 4. Ceramic capacitors must always be placed a sufficient minimum distance from the edge of the circuit board. High bending forces may be exerted there when the panels are separated and during further processing of the board (such as when incorporating it into a housing).
- 5. Ceramic capacitors should always be placed parallel to the possible bending axis of the circuit board.
- 6. No screw connections should be used to fix the board or to connect several boards. Components should not be placed near screw holes. If screw connections are unavoidable, they must be cushioned (for instance by rubber pads).

10



Cautions and warnings

The following should be considered in the placement process

- 1. Ensure correct positioning of the ceramic capacitor on the solder pad.
- 2. Caution when using casting, injection-molded and molding compounds and cleaning agents, as these may damage the capacitor.
- 3. Support the circuit board and reduce the placement forces.
- 4. A board should not be straightened (manually) if it has been distorted by soldering.
- 5. Separate panels with a peripheral saw, or better with a milling head (no dicing or breaking).
- 6. Caution in the subsequent placement of heavy or leaded components (e.g. transformers or snap-in components): danger of bending and fracture.
- 7. When testing, transporting, packing or incorporating the board, avoid any deformation of the board not to damage the components.
- 8. Avoid the use of excessive force when plugging a connector into a device soldered onto the board.
- 9. Ceramic capacitors must be soldered only by the mode (reflow or wave soldering) permissible for them (see the chapter "Soldering directions").
- 10. When soldering the most gentle solder profile feasible should be selected (heating time, peak temperature, cooling time) in order to avoid thermal stresses and damage.
- 11. Ensure the correct solder meniscus height and solder quantity.
- 12. Ensure correct dosing of the cement quantity.
- 13. Ceramic capacitors with an AgPd external termination are not suited for the lead-free solder process: they were developed only for conductive adhesion technology.

This listing does not claim to be complete, but merely reflects the experience of EPCOS AG.



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